

# Elizabeth Mountz

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(412) 396-9423

## SUMMARY

ECE Masters student at Carnegie Mellon University graduating in December 2024 with a specialty in analog/mixed-signal integrated circuit design and photonic MEMS design. Seeking full-time opportunities to expand design portfolio in integrated sensing/wireless communications applications.

## EDUCATION

**CARNEGIE MELLON UNIVERSITY** Pittsburgh, PA  
*Master of Electrical Engineering* 12/24

GPA: 3.92

- **THESIS:** Acousto-Optic Resonator Design for Beam Steering Applications
- **RELEVANT GRADUATE COURSEWORK:** Analog IC Design; Advanced Digital IC Design; RF IC Implementation; IC Verification; Design, Integration, and Tape-out of IoT Systems; Nanofabrication Lab; Computational Photography
- **AFFILIATIONS:** Micro and Nano Systems Laboratory, Integrated Circuits and Bioengineering Lab, Biorobotics Lab
- **INTERESTS:** Private Pilot License, Carnegie Mellon University Small Ensemble (Oboist)

**UNIVERSITY OF PITTSBURGH** Pittsburgh, PA  
*Bachelor of Science in Bioengineering* 5/22

GPA: 3.6

## EXPERIENCE

**QORVO** Fort Lauderdale, FL  
*Analog IC Design Intern* 5/24-8/24

- Completed comprehensive training in SPICE simulation tools
- Presented circuit design and simulation results to broader SoC engineering and executive team
- Ported switched capacitor scaler circuit to advanced technology node and characterized analog switch design charge injection, speed, static/dynamic power consumption, and DC impedance

**MIXED-SIGNAL TAPEOUT; DIRECT DIGITAL SYNTHESIZER** Pittsburgh, PA  
*Course Project; CMU-Apple Silicon Initiative* 1/24-5/24

- Proposed mixed-signal Direct Digital Synthesis (DDS) chip for ultrasonic transducer phased array control
- Designed in Cadence Virtuoso with 22nm TSMC Process 8-bit unary current steering DAC schematic and layout
- Characterized in simulation DAC performance at temperature/power/process corners

**MIXED-SIGNAL TAPEOUT; CMOS IMAGE SENSOR** Pittsburgh, PA  
*Course Project; CMU-Apple Silicon Initiative* 8/24-present

- Learning fundamentals of system-level chip design, including digital timing, peripheral circuitry, and whole chip integration/simulation
- Working in teams on circuit design blocks in Cadence (65nm TSMC process), including DAC, comparator, counter, scan chain, I/O, digital processor

**CHIP VERIFICATION** Pittsburgh, PA  
*Course Project; CMU-Apple Silicon Initiative* 8/24-present

- Verifying previous direct digital synthesizer chip tape-out by designing and fabricating a test PCB, conducting chip bring-up, and debugging any unexpected behaviors

**MICROELECTROMECHANICAL SYSTEMS (MEMS) DESIGN** Pittsburgh, PA  
*Graduate Research* 8/23 - present

- Optimized electro-mechanical coupling coefficient in Surface Acoustic Wave (SAW) transducer design using COMSOL Multiphysics simulation with ongoing objective of fabricating the device with the optimized parameters
- Configured and documented cloud computing and batch processing methods for faster parameter sweeps in transducer simulations

**HEBI ROBOTICS** Pittsburgh, PA  
*Electrical Engineering Intern* 5/23 - 8/23

- Designed schematic and PCB layout in Altium for internal development use including 4-channel Ethernet/optical fiber switch, 4-channel brushed DC motor driver with motor coil current sensing, and a 160W Eload with active cooling, on-board current/voltage sensing, and thermal regulation.

**SKYDIO** San Francisco, CA  
*Electrical Engineering Intern* 5/22 - 12/22

- Designed schematic and 6-layer PCB in Cadence PCB Suite for two iterations of a product, and a test fixture board
- Collaborated with product development team to meet size constraints of product form-factor and with the system integration team for final component testing and selection
- Worked closely with firmware team on STM32 MCU selection, integration in design, and firmware bring-up

## SKILLS

- Analog/Mixed-Signal/RF IC Design
- SPICE Simulation
- Cadence Virtuoso ADE and Layout Suite
- COMSOL Multiphysics Simulation
- Nanofabrication
- Multi-Layer PCB Design (Cadence and Altium)
- Optical System Design and Simulation (Ansys)
- Image Processing